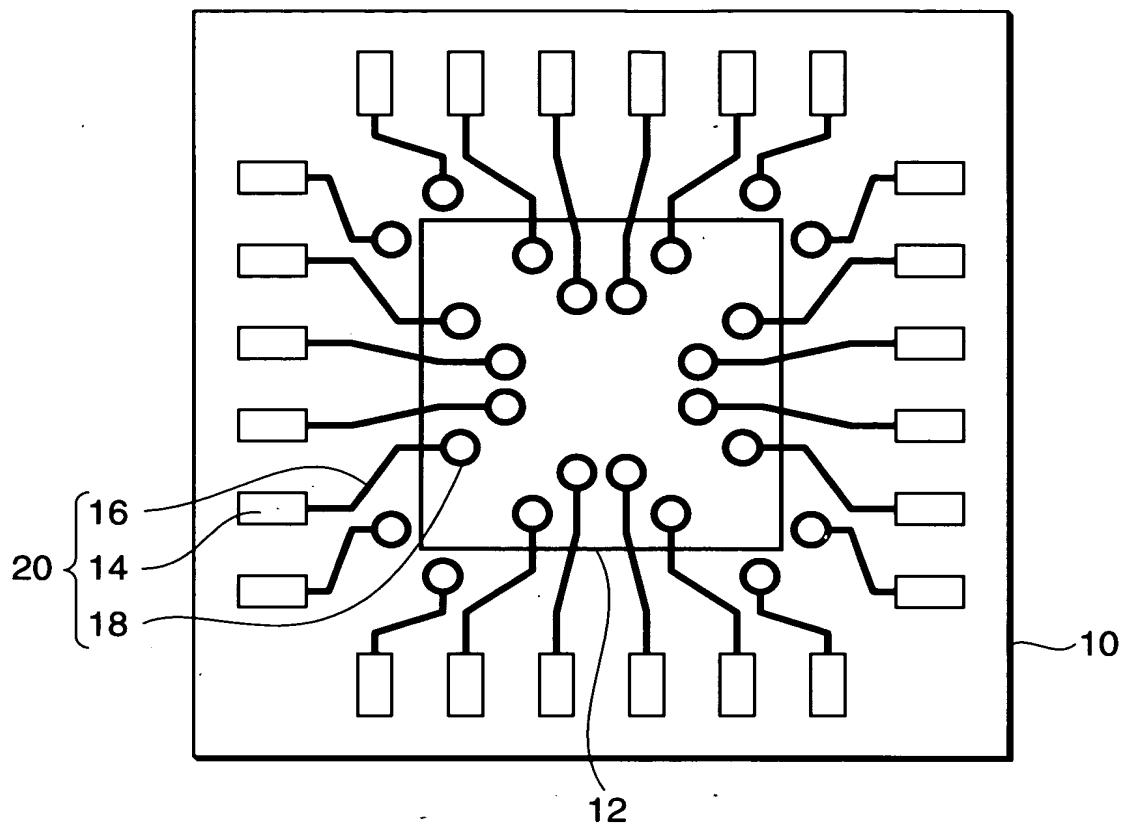


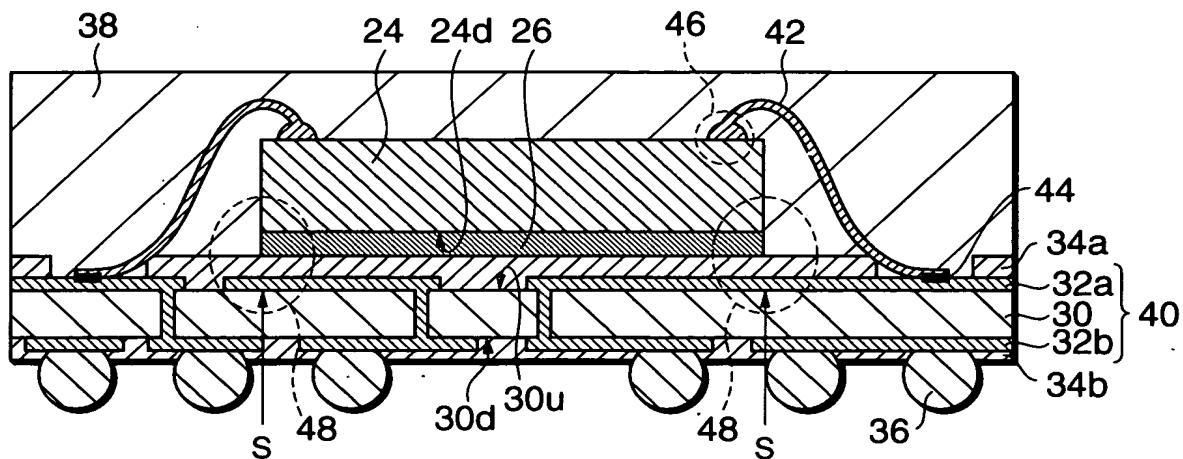
1/4

Fig. 1



PLAN VIEW OF SEMICONDUCTOR DEVICE HAVING CONVENTIONAL BGA PACKAGE STRUCTURE

Fig. 2



CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE HAVING CONVENTIONAL BGA PACKAGE STRUCTURE

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Fig. 3

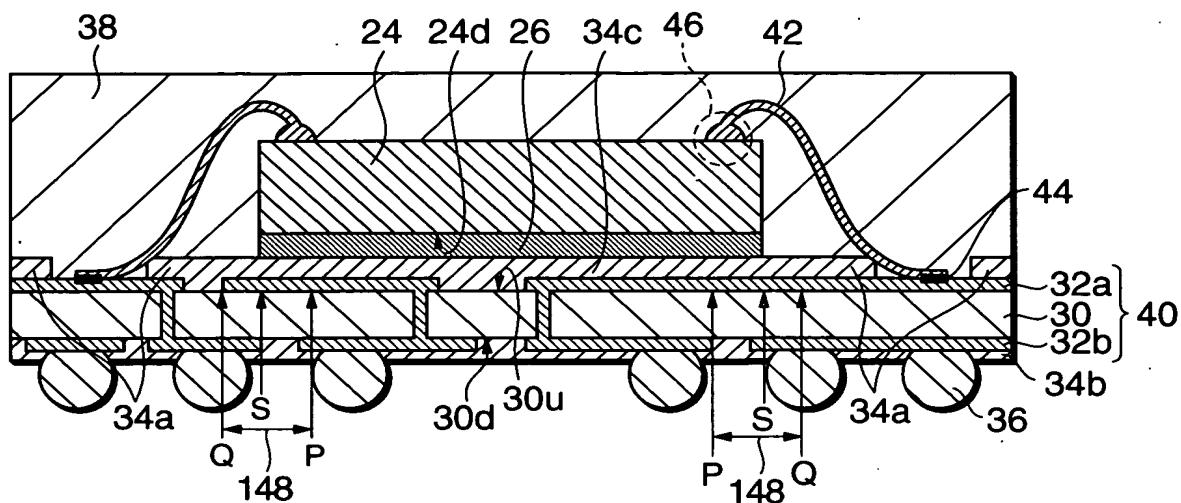
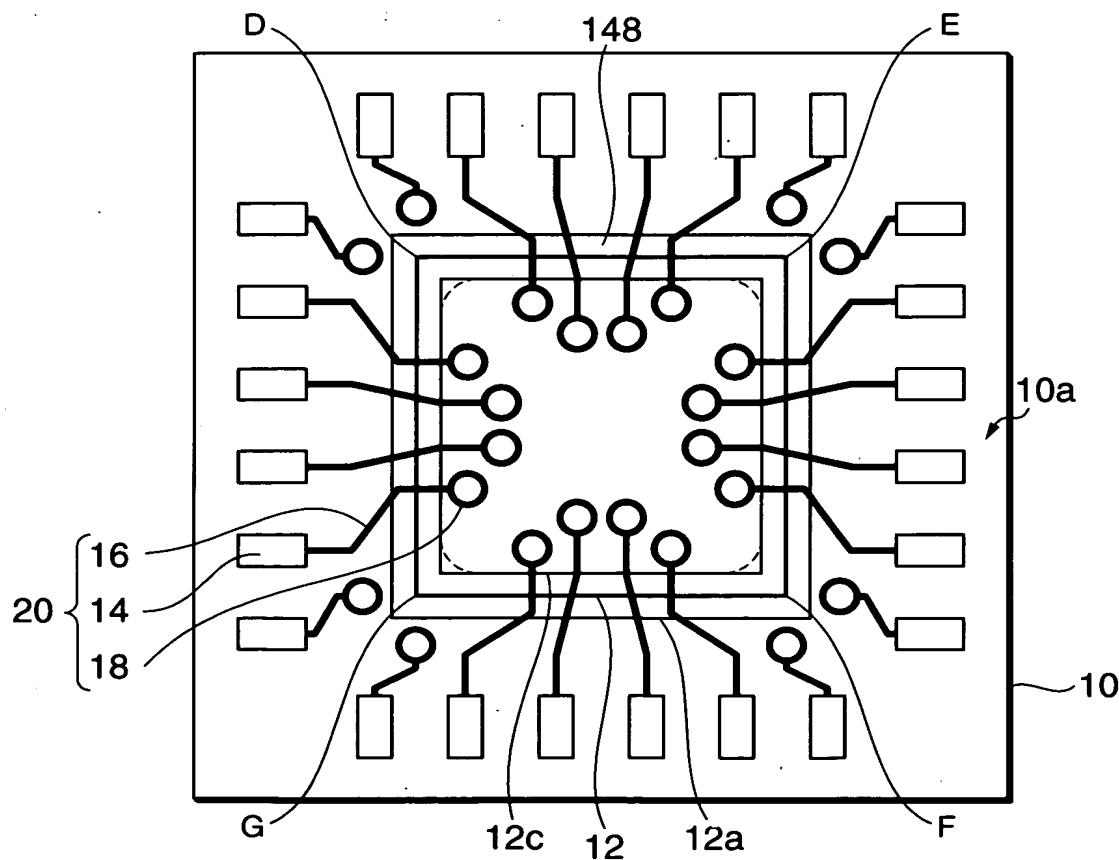
CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE  
ACCORDING TO FIRST EMBODIMENT

Fig. 4

PLAN VIEW OF SEMICONDUCTOR DEVICE  
ACCORDING TO FIRST EMBODIMENT

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Fig. 5A

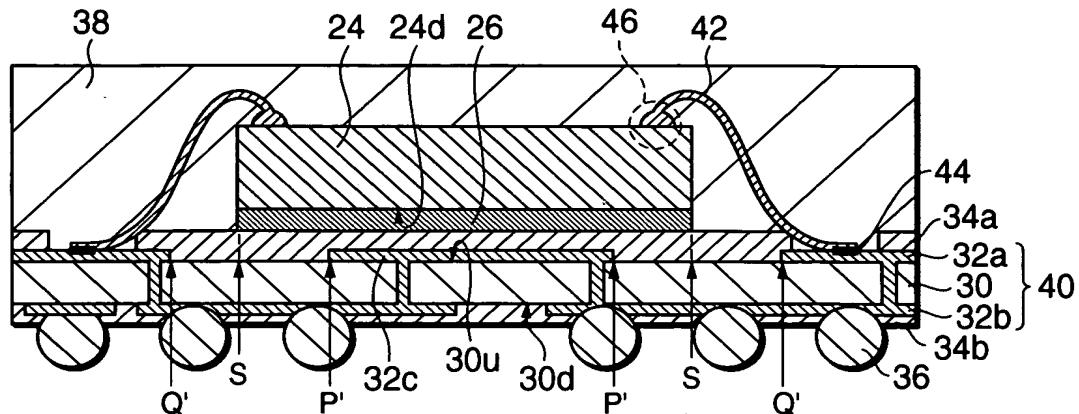


Fig. 5B

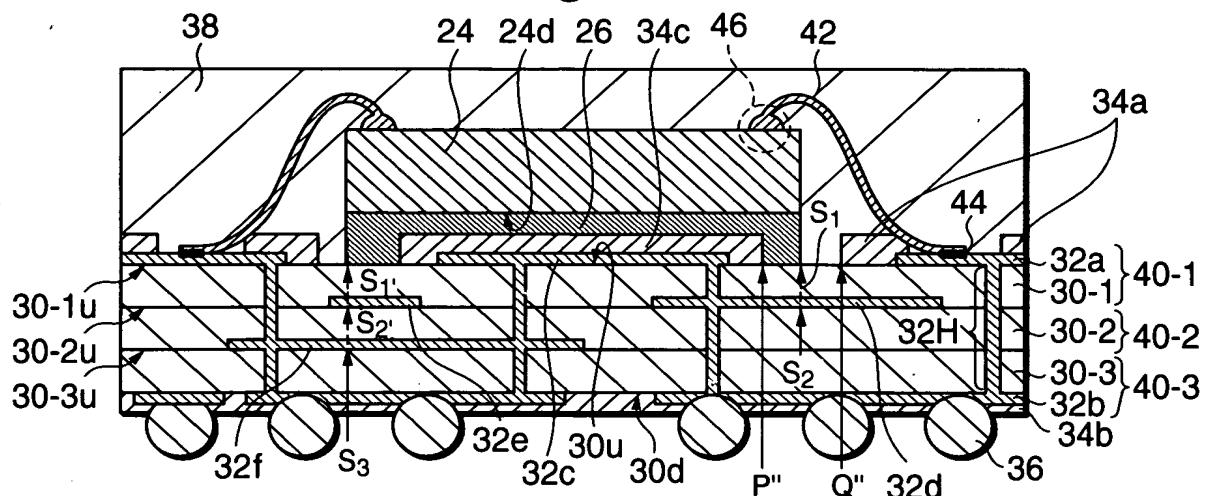
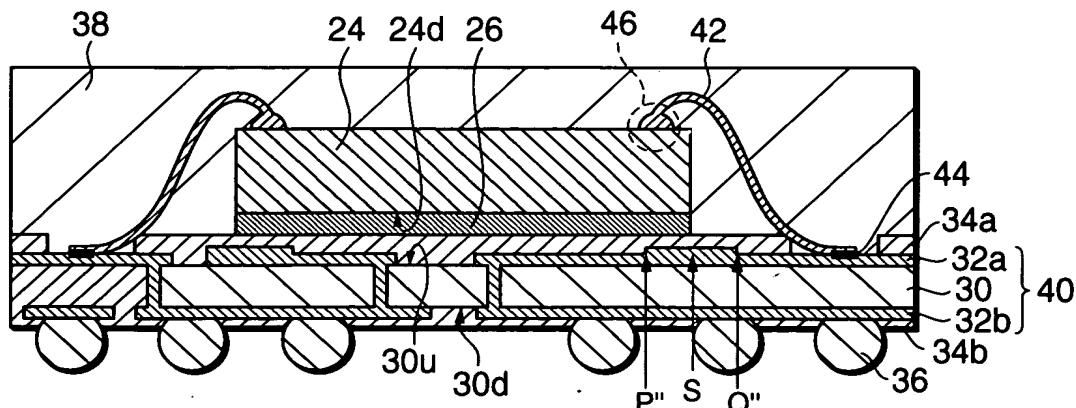
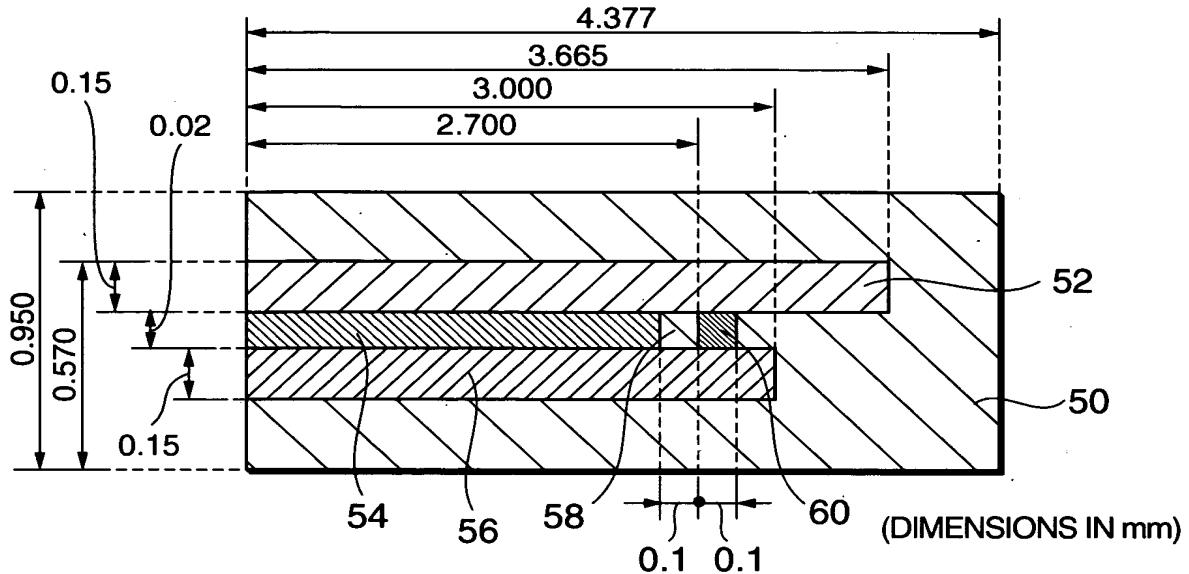
CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE  
ACCORDING TO SECOND EMBODIMENT

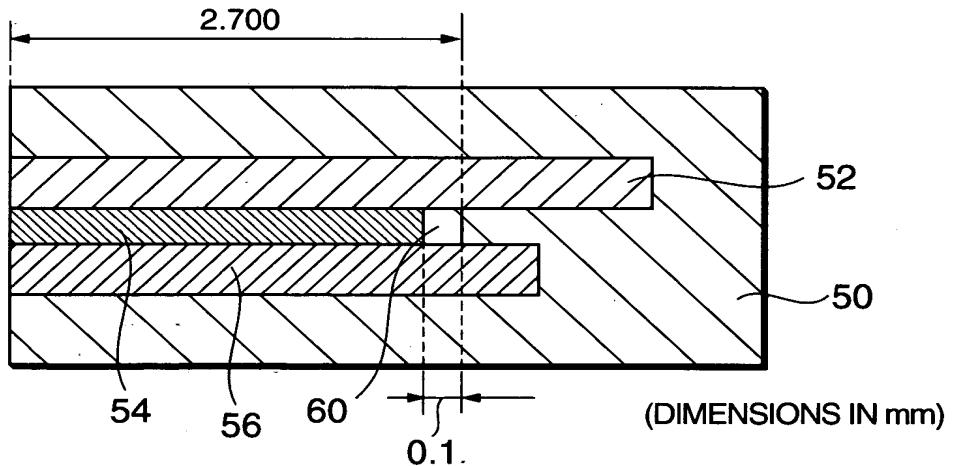
Fig. 6

CROSS-SECTIONAL VIEW OF SEMICONDUCTOR DEVICE  
ACCORDING TO THIRD EMBODIMENT

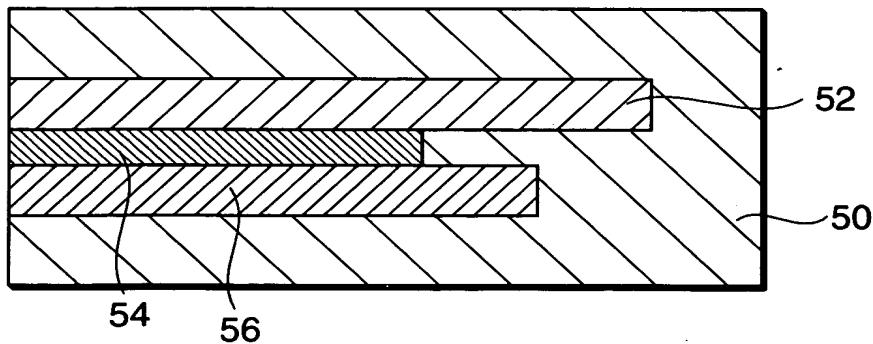
4/4  
**Fig. 7A**



**Fig. 7B**



**Fig. 7C**



SCHEMATIC CROSS-SECTIONAL VIEW OF QUASI SEMICONDUCTOR DEVICE